Freeform Search

Database: US Pre-Grant Publication Full-Text Database
US Patents Full-Text Database
US OCR Full-Text Database
EPO Abstracts Database
JPO Abstracts Database
Derwent World Patents Index
IBM Technical Disclosure Bulletins

Term: L32 and (temperature sens$3 or thermal$2 sens$3)

Display: 10 **Documents in Display Format:** - **Starting with Number** 1

Generate: ○ **Hit List** ◉ **Hit Count** ○ **Side by Side** ○ **Image**

Search Clear Interrupt

Search History

DATE: Friday, October 05, 2007 **Purge Queries** Printable Copy Create Case

Set Name side by side	Query	Hit Count	Set Name result set
	DB=PGPB,USPT,USOC,EPAB,JPAB; PLUR=YES; OP=ADJ		
L34	6679628[uref]	12	L34
L33	L32 and (temperature sens$3 or thermal$2 sens$3)	176	L33
L32	L30 and (substrate or die or IC or integrated circuit or printed circuit or chip)	451	L32
L31	L30 and (second substrate or second die or second chip or separate substrate or separate die or separate chip or second IC or separate IC or second integrated circuit or separate integrated circuit or second printed near circuit or separate printed near circuit)	18	L31
L30	L24 and (dual diode or dual transistor or second diode or second transistor or identical diodes or identical transistors)	630	L30
L29	L27 and (semiconductor or substrate or silicon substrate or chip or integrated circuit or IC)	201	L29
L28	L27 and (semiconductor or substrate or silicon subdtrate or chip or integrated circuit or IC)	201	L28
L27	L26 and (calibrati$3 or offset or lineari$4 or temperature near compensat$3)	214	L27
L26	L25 and (gain or amplifier or comparator)	300	L26
L25	L24 and (band gap or bandgap)	373	L25

L24	(374/170,171,172,173,178;702/130,99;327/512,513;257/467,470)![CCLS]	4864	L24
L23	(374/170,171,172,173;702/130,99;327/512,513;257/467,470)![CCLS]	4613	L23
	DB=PGPB,USPT,USOC,EPAB,JPAB,DWPI,TDBD; PLUR=YES; OP=ADJ		
L22	L20 and (band gap)	30	L22
L21	L20 and (bandgap)	19	L21
L20	L19 and (temperature sensor)	846	L20
L19	(substrate near temperature) and (silicon substrate)	13308	L19
L18	(three terminal chip)	16	L18
L17	L16 and (three terminal)	96	L17
L16	374/$.ccls.	29795	L16
L15	three terminal near integrated circuit	45	L15
	DB=USPT; PLUR=YES; OP=ADJ		
L14	L13 and (calibrat$3)	1	L14
L13	6252209.pn.	1	L13
L12	L10 and (terminal$1)	1	L12
L11	L10 and (output)	1	L11
L10	6055489.pn.	1	L10
	DB=PGPB; PLUR=YES; OP=ADJ		
L9	L8 and (terminals)	1	L9
L8	20050099752	1	L8
	DB=PGPB,USPT,USOC,EPAB,JPAB,DWPI,TDBD; PLUR=YES; OP=ADJ		
L7	L6 and (bandgap)	12	L7
L6	semiconductor near temperature near sens$3	611	L6
L5	L3 and (chip or substrate or integrated circuit or IC)	99	L5
L4	L3 and (bandgap)	1	L4
L3	(thermocouple) near (semiconductor)	227	L3
	DB=USPT; PLUR=YES; OP=ADJ		
L2	L1 and (temperature sensor)	1	L2
L1	6055489.pn.	1	L1

END OF SEARCH HISTORY

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